

A new arrival in SET service team

SET continues reinforcing his team welcoming **Jean-Charles Roux**, new service and application engineer. Jean-Charles as Matthew, François and Laurent will take care of the demo and bonding tests at SET, acceptance and installation of SET equipment, and their maintenance worldwide.



ACCμRA Family: A complete range of equipment



ACCμRA Family composed by the **ACCμRA100**, **ACCμRA OPTO** and **ACCμRA M** answer all your needs.

The **ACCμRA100** and **ACCμRA OPTO** are semi-automatic flip-chip bonders that allows $\pm 0.5 \mu\text{m}$ post-bonding accuracy. Their flexibility makes them ideal for developing a wide range of applications.

The **ACCμRA100** with its high force capabilities is the perfect equipment for applications using sintering and thermo-compression.

The **ACCμRA OPTO** is well adapted for your optoelectronics applications (i.e. assembly of laser diodes, laser bars and photodiodes, lenses...) which require high precision and very good control at low forces.

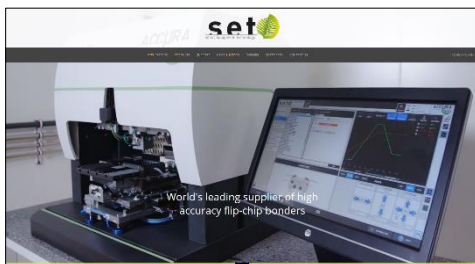


ACCμRA M is a manual machine with a post-bond accuracy of $\pm 5 \mu\text{m}$. The motorized bonding arm allows to control very precisely the force. Combined with the temperature controller, it guarantees a perfect quality and repeatability of process.

ACCμRAs equipment are available at SET, we will be very pleased to welcome you for a demo.

SET labeled BPI Excellence for the second year

SET was chosen by BPI France for a second time to be certified BPI Excellence. This label was created by the French Bank of Investment in order to reward companies for their performances, dynamism, innovation and reliability. SET is proud to have been labeled as BPI France Excellence for the second year.



Discover our brand new website

The entire SET team is pleased to present you our brand new website, with improved ergonomics, new pictures and revised descriptions.

The website is now available in three languages: English, French and German.

Demo center at SET

Because high precision flip-chip applications are very demanding and several parameters influence the bonding process and quality, SET continues its policy to welcome customers in its facilities. The purpose is to help them to develop their process and run their pilot production.

A new **FC150** dedicated to demo is available since March 2017 in Saint-Jeoire. **ACCμRAs equipment and FC300** are also available for bonding tests.

More than 30 days of demos from 12 potential customers have already been done since then. Our team is fully available to discuss processes, support the set-up of new applications and bond components to propose the configuration that fits best to our customers' needs. Please feel free to contact us if you need some assistance in your flip-chip activity.

Exhibitions and Conferences: when and where meeting SET in 2017

SET already attended this year to **Semicon Korea** on the booth of our local agent **Woowon**.

SET also attended to **Semicon China** with the support of our local agent **SÜSS MicroTec China**, the ACCμRA OPTO was exposed on our booth.



Semicon China 2017

SET was also present at the **European 3D Summit** in France and in Smart System Integration in Cork (Ireland).

In addition, SET will take part, with the kind collaboration of our local agents, to the forthcoming fairs and conferences:

- **SMT** (Nüremberg, Germany) – May 16/18th
- **MiNaPad** (Grenoble, France) – May 17/18th
- **ECTC** (Lake Buena Vista, USA) – May 30th/June 2nd
- **Nordic Conference** (Goteborg, Sweden) - June 18/20th
- **Semicon West** (San Francisco, USA) - July 11/13th
- **CIOE** (Shenzen, China) – September 6/9th
- **Semicon Taiwan** (Taipei, France) – September 13/15th
- **EPMC** (Warsaw, Poland) - September 10/13th
- **MEMS Summit** (Grenoble, France) - September 21/22th
- **MIDEM** (Ljubljana, Slovenia) - October 4/6th
- **IWLPC** (San Jose, USA) - October 24/26th
- **Semicon Europa/Productronica** (Munich, Germany) - October 25/27th
- **Semicon Japan** (Tokyo, Japan) – December 13/15th
- **IWPSD** (Delhi, India) – December 11/15th

We will present our latest machines, developments and technical support soon and thank you for your attention.